

Title (en)
METHOD FOR THE MANUFACTURE OF AN ELECTRONIC ASSEMBLY

Title (de)
VERFAHREN ZUR HERSTELLUNG EINER ELEKTRONISCHEN BAUGRUPPE

Title (fr)
PROCÉDÉ DE FABRICATION D'UN MODULE ÉLECTRONIQUE

Publication
EP 2289100 A2 20110302 (DE)

Application
EP 09765709 A 20090525

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Abstract (en)
[origin: WO2009153129A2] The invention relates to a method for the manufacture of an electronic assembly, comprising at least one electronic component (9) and also a conductor track structure (7) which is used to make contact with the at least one electronic component (9). The method involves a first step being used to pattern a conductive foil (1) to produce the conductor track structure (7). In a second step, the conductor track structure (7) has the at least one electronic component (9) fitted. In a final step, a further foil is laminated onto the conductive foil (1) fitted with the at least one electronic component (9) on the side on which the conductive foil (1) has the at least one electronic component (9) fitted.

IPC 8 full level
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Citation (search report)
See references of WO 2009153129A2

Citation (examination)
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